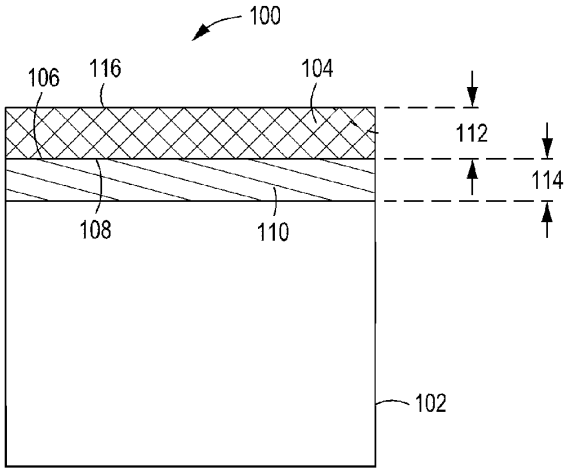

100
106
116
104
112
114
108
110
102

FIG. 1

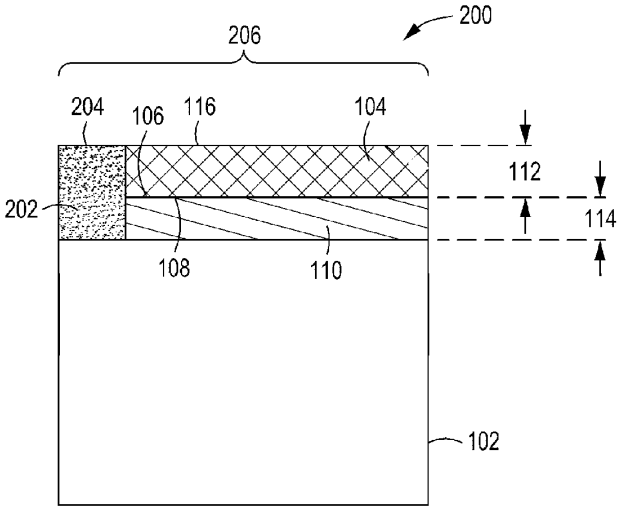

200
206
204
106
116
104
112
202
114
108
110
102

FIG. 2

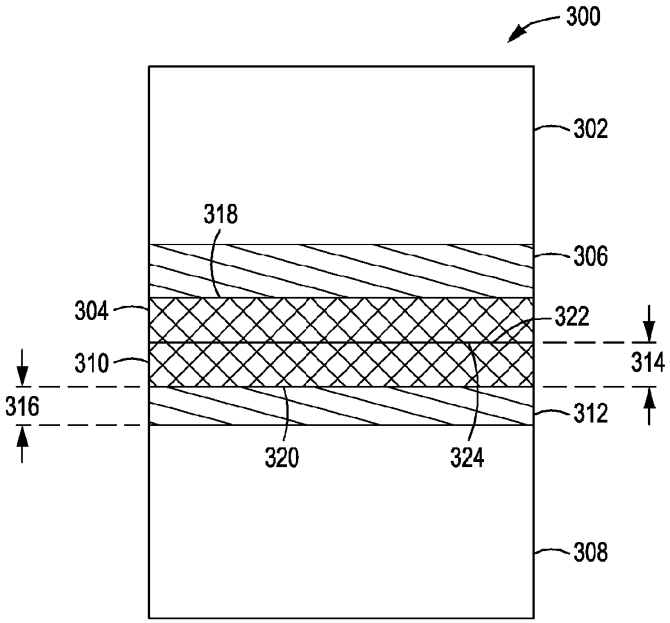

300
302
318
306
304
322
314
310
316
312
320
324
308

FIG. 3

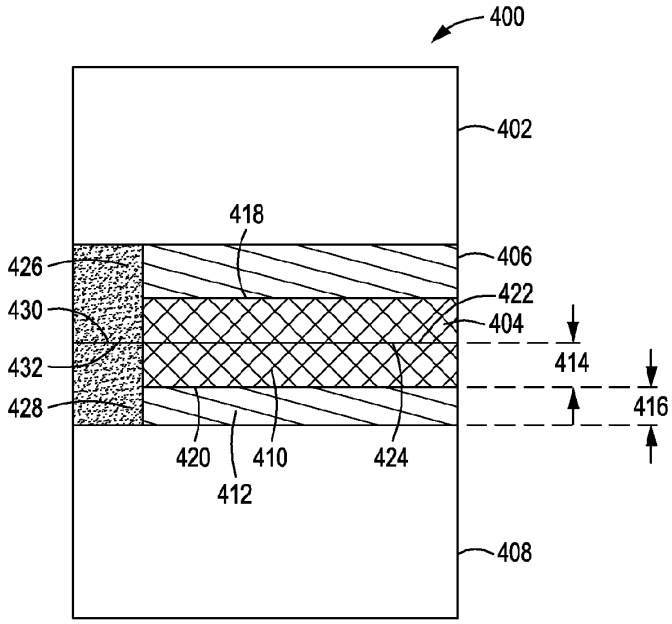

400
402
418
406
426
422
430
404
414
432
416
428
420
410
424
412
408

FIG. 4

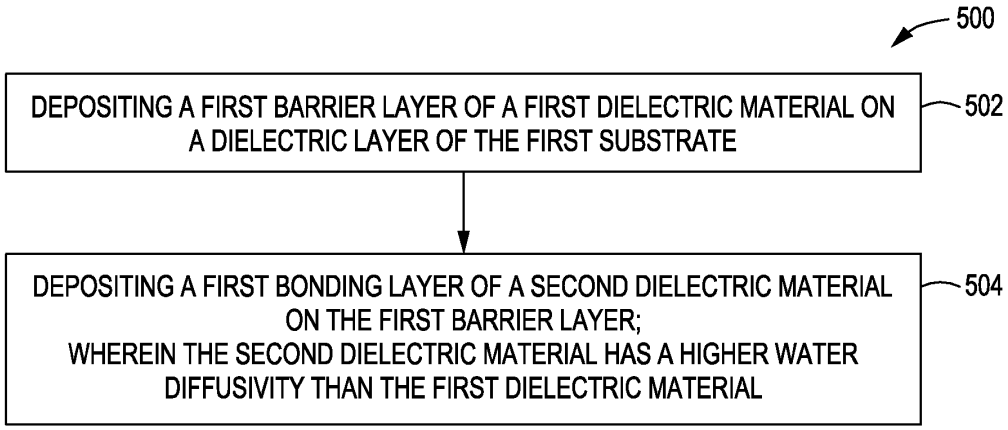

500
DEPOSITING A FIRST BARRIER LAYER OF A FIRST DIELECTRIC MATERIAL ON A DIELECTRIC LAYER OF THE FIRST SUBSTRATE
502
DEPOSITING A FIRST BONDING LAYER OF A SECOND DIELECTRIC MATERIAL ON THE FIRST BARRIER LAYER;
WHEREIN THE SECOND DIELECTRIC MATERIAL HAS A HIGHER WATER DIFFUSIVITY THAN THE FIRST DIELECTRIC MATERIAL
504

FIG. 5